

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1. (previously presented) An electrodeposited copper foil with low roughness surface, wherein surface roughness ( $R_z$ ) is 2.0  $\mu\text{m}$  or less, surface uniformity is provided with degree of mirror gloss of the roughness surface, measured by  $G_s$  ( $85^\circ$ ) in accordance with JIS (Japanese Industrial Standard) Z 8741 is 100 or more and low roughness without uneven surge, and a percent elongation is 10.0% or higher at  $180^\circ\text{C}$ .
2. (canceled)
3. (original) A process for producing an electrodeposited copper foil with low roughness surface having surface roughness ( $R_z$ ) of 2.0  $\mu\text{m}$  or less, surface uniformity provided with low roughness without uneven surge and exhibiting a percent elongation of 10.0% or higher at  $180^\circ\text{C}$ , comprising passing a direct current between an insoluble anode consisting of a titanium plate coated with a Platinum Group element or oxide thereof and a titanium drum as a cathode counter to the anode in an electrolyte of an aqueous solution of sulfuric acid/copper

sulfate, wherein said electrolyte contains an oxyethylene surfactant, a polyethyleneimine or its derivative, a sulfonate of active organosulfur compound and chloride ions.

4. (original) The process for producing an electrodeposited copper foil with low roughness surface according to claim 3, wherein degree of mirror gloss of the roughness surface, measured by Gs (85°) in accordance with JIS Z 8741 is 100 or more in the electrodeposited copper foil with low roughness surface.

5. (currently amended) The process for producing an electrodeposited copper foil with low roughness surface according to claim 3 ~~or 4~~, wherein concentration of oxyethylene surfactant in the electrolyte is in the range of 10 to 200 mg/L.

6. (currently amended) The process for producing an electrodeposited copper foil with low roughness surface according to claim 3 ~~or 4~~, wherein concentration of polyethyleneimine or its derivative in the electrolyte is in the range of 0.5 to 30.0 mg/L.

7. (currently amended) The process for producing an electrodeposited copper foil with low roughness surface according to claim 3 ~~or 4~~, wherein concentration of sulfonate of active

organosulfur compound in the electrolyte is in the range of 5.5 to 450  $\mu\text{mol/L}$ .

8. (currently amended) The process for producing an electrodeposited copper foil with low roughness surface according to claim 3 ~~or 4~~, wherein concentration of chloride ions in the electrolyte is in the range of 20 to 120 mg/L.

9. (new) The process for producing an electrodeposited copper foil with low roughness surface according to claim 4, wherein concentration of oxyethylene surfactant in the electrolyte is in the range of 10 to 200 mg/L.

10. (new) The process for producing an electrodeposited copper foil with low roughness surface according to claim 4, wherein concentration of polyethyleneimine or its derivative in the electrolyte is in the range of 0.5 to 30.0 mg/L.

11. (new) The process for producing an electrodeposited copper foil with low roughness surface according to claim 4, wherein concentration of sulfonate of active organosulfur compound in the electrolyte is in the range of 5.5 to 450  $\mu\text{mol/L}$ .

12. (new) The process for producing an electrodeposited copper

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foil with low roughness surface according to claim 4, wherein concentration of chloride ions in the electrolyte is in the range of 20 to 120 mg/L.